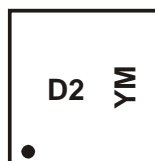


## Marking Information

Site 1



D2 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: H = 2020)  
 M = Month (ex: 9 = September)

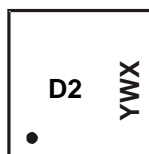
Date Code Key

Year	2012	...	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	Z	...	H	I	J	K	L	M	N	O	P	R

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Site 2



D2 = Product Type Marking Code  
 YWX = Date Code Marking  
 Y = Year (ex: 0 = 2020)  
 W = Week (ex: a = Week 27; z Represents Week 52 and 53)  
 X = Internal Code (ex: U = Monday)

Date Code Key

Year	2012	...	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	2	...	0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Y	Z

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 N-Channel	Q2 P-Channel	Unit
Drain-Source Voltage			V <sub>DSS</sub>	12	-12	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	±8	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	5.6 4.4	-3.8 -3.0	A
	t < 5s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	7.2 5.8	-5.0 -4.0	A
Maximum Continuous Body Diode Forward Current (Note 5)			I <sub>S</sub>	1	-1	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	20	-15	A

**Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	Steady State	P <sub>D</sub>	1.4	W
	t < 5s		2.2	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>θJA</sub>	92	°C/W
	t < 5s		55	
Thermal Resistance, Junction to Case (Note 5)		R <sub>θJC</sub>	30	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Note: 5. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. copper, single sided.

**Electrical Characteristics Q1 N-Channel** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b> (Note 6)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	12	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	—	—	1.0	μA	V <sub>DS</sub> = 12V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±8V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b> (Note 6)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.4	—	1	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	17	29	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A
		—	20	34		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 4.6A
		—	24	44		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 4.1A
		—	30	65		V <sub>GS</sub> = 1.5V, I <sub>D</sub> = 2A
Forward Transfer Admittance	Y <sub>fs</sub>	—	6.5	—	s	V <sub>DS</sub> = 10V, I <sub>D</sub> = 5A
Diode Forward Voltage	V <sub>SD</sub>	—	0.6	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A
<b>DYNAMIC CHARACTERISTICS</b> (Note 7)						
Input Capacitance	C <sub>iss</sub>	—	914	—	pF	V <sub>DS</sub> = 6V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	132	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	119	—	pF	
Gate Resistance	R <sub>g</sub>	—	1.26	—	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Q <sub>g</sub>	—	10.5	—	nC	V <sub>DS</sub> = 6V, I <sub>D</sub> = 6.5A
Total Gate Charge (V <sub>GS</sub> = 8V)		—	19.6	—	nC	
Gate-Source Charge	Q <sub>gs</sub>	—	1.2	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	1.6	—	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	—	5.0	—	ns	V <sub>DD</sub> = 6V, V <sub>GS</sub> = 4.5V, R <sub>L</sub> = 1.2Ω, R <sub>G</sub> = 1Ω
Turn-On Rise Time	t <sub>r</sub>	—	10.5	—	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	—	16.6	—	ns	
Turn-Off Fall Time	t <sub>f</sub>	—	4.1	—	ns	

**Electrical Characteristics Q2 P-Channel** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b> (Note 6)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-12	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	—	—	-1.0	μA	V <sub>DS</sub> = -12V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±8V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b> (Note 6)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.4	—	-1	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	37	61	mΩ	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.6A
		—	47	81		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -3.2A
		—	63	115		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -1A
		—	90	170		V <sub>GS</sub> = -1.5V, I <sub>D</sub> = -1A
Forward Transfer Admittance	Y <sub>fs</sub>	—	5.5	—	s	V <sub>DS</sub> = -10V, I <sub>D</sub> = -3.6A
Diode Forward Voltage	V <sub>SD</sub>	—	-0.65	-1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A
<b>DYNAMIC CHARACTERISTICS</b> (Note 7)						
Input Capacitance	C <sub>iss</sub>	—	915	—	pF	V <sub>DS</sub> = -6V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	225	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	183	—	pF	
Gate Resistance	R <sub>g</sub>	—	56.9	—	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Q <sub>g</sub>	—	10.7	—	nC	V <sub>DS</sub> = -6V, I <sub>D</sub> = -4.3A
Total Gate Charge (V <sub>GS</sub> = -8V)		—	17.9	—	nC	
Gate-Source Charge	Q <sub>gs</sub>	—	1.7	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	3.0	—	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	—	5.7	—	ns	V <sub>DD</sub> = -6V, V <sub>GS</sub> = -4.5V, R <sub>L</sub> = 1.6Ω, R <sub>G</sub> = 1Ω
Turn-On Rise Time	t <sub>r</sub>	—	11.5	—	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	—	27.8	—	ns	
Turn-Off Fall Time	t <sub>f</sub>	—	26.4	—	ns	

Notes: 6. Short duration pulse test used to minimize self-heating effect.  
7. Guaranteed by design. Not subject to product testing.

# Q1 N-CHANNEL

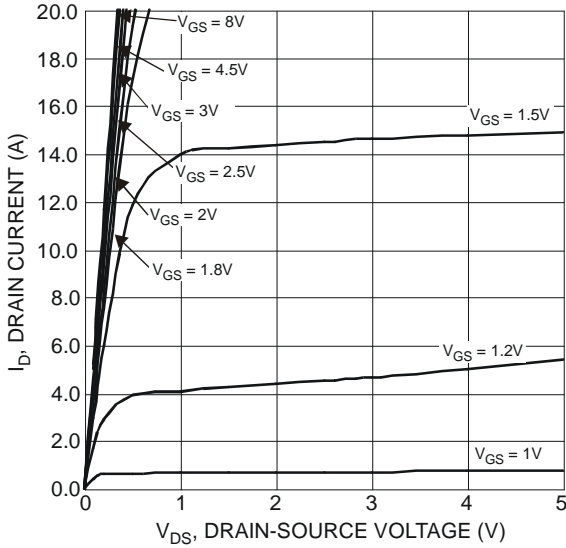


Figure 1 Typical Output Characteristics

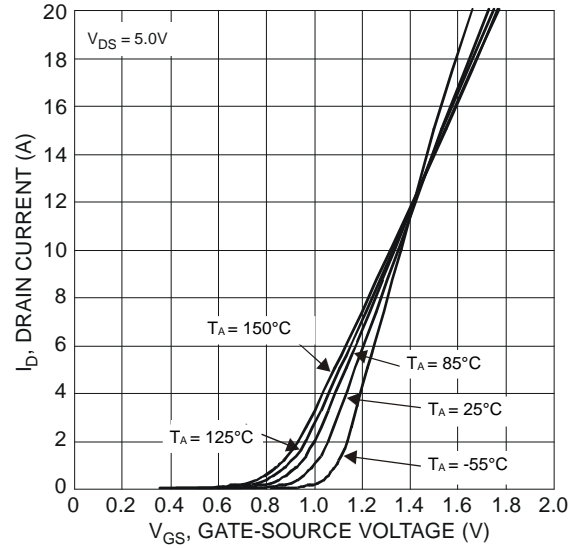


Figure 2 Typical Transfer Characteristics

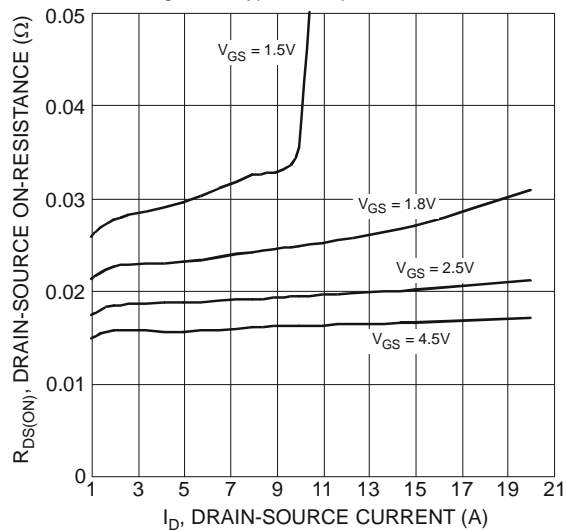


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

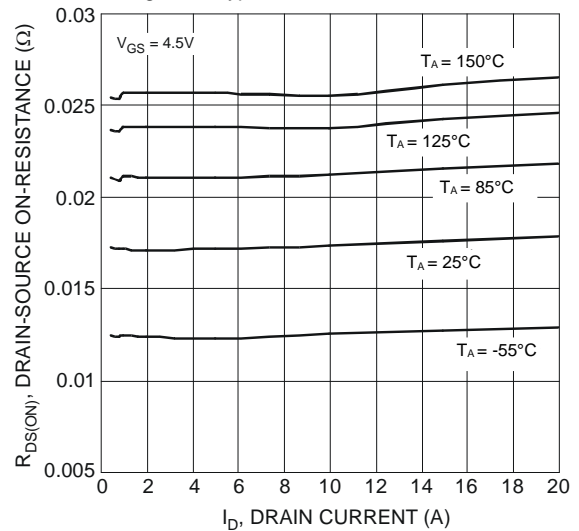


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

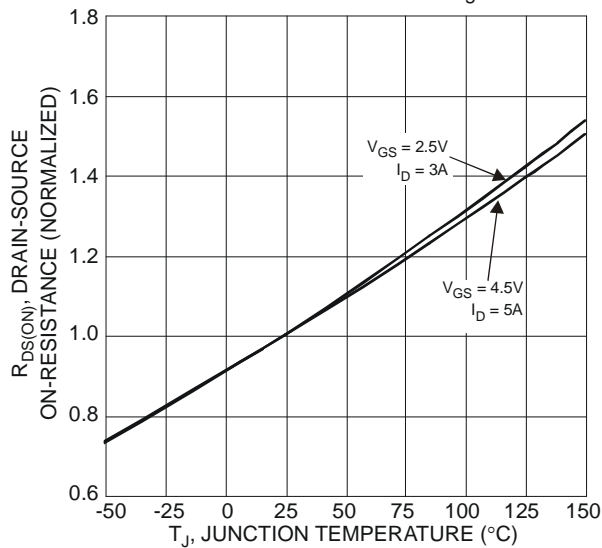


Figure 5 On-Resistance Variation with Temperature

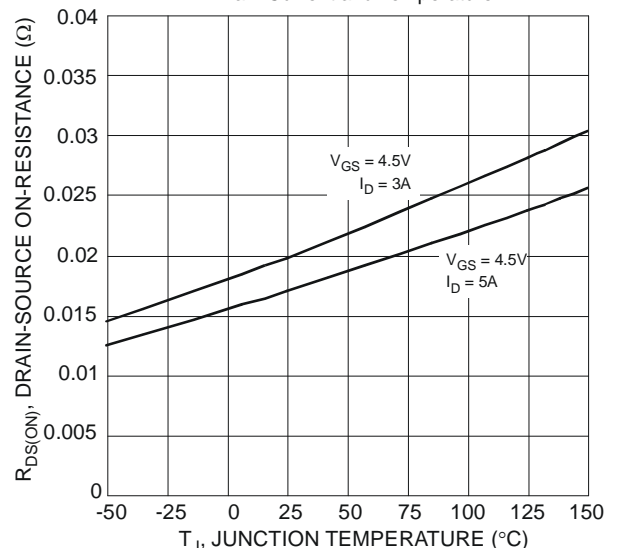


Figure 6 On-Resistance Variation with Temperature

**Q1 N-CHANNEL** (continued)

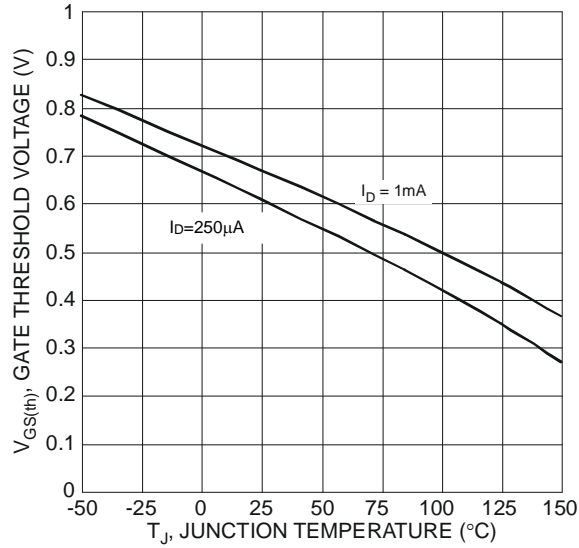


Figure 7 Gate Threshold Variation vs. Junction Temperature

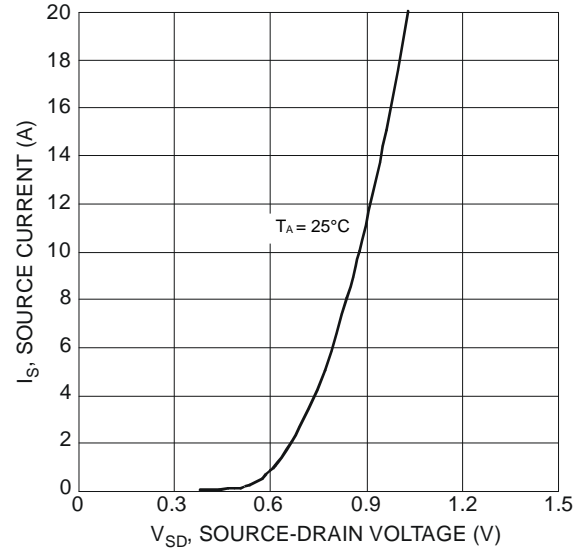


Figure 8 Diode Forward Voltage vs. Current

## Q2 P-CHANNEL

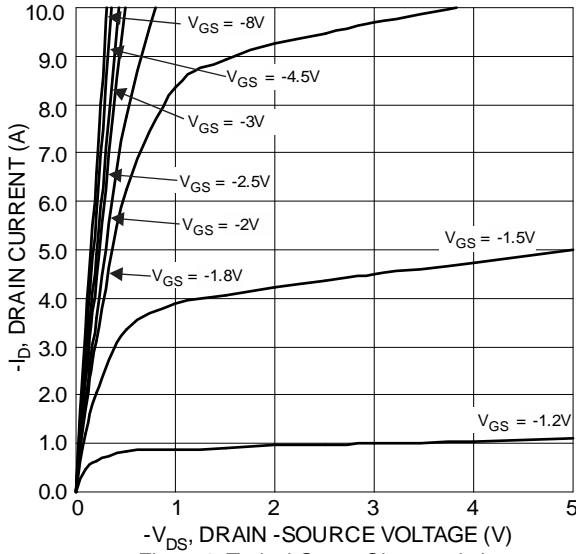


Figure 9 Typical Output Characteristics

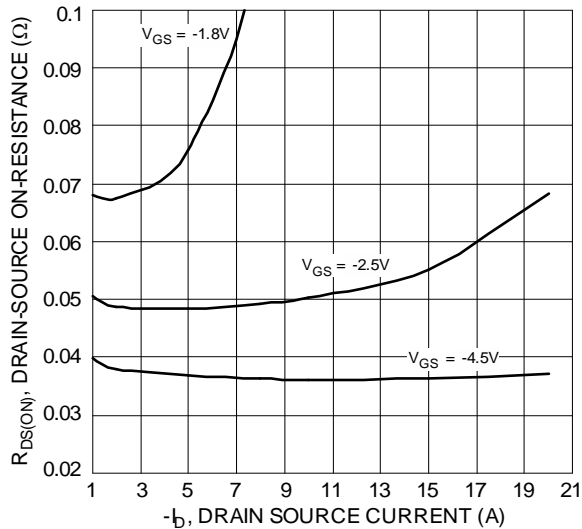


Figure 11 Typical On-Resistance vs. Drain Current and Gate Voltage

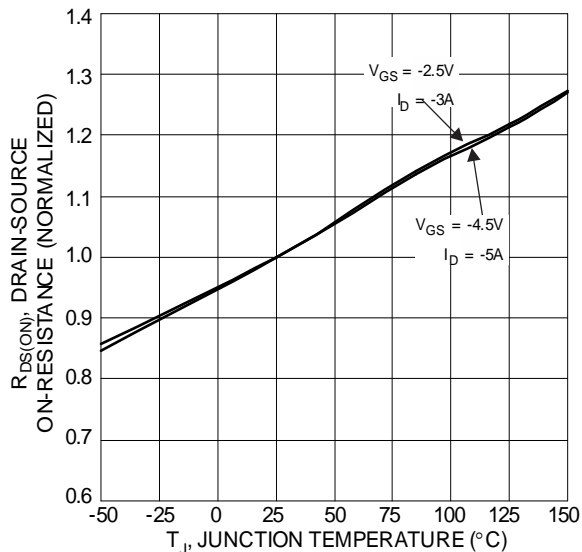


Figure 13 On-Resistance Variation with Temperature

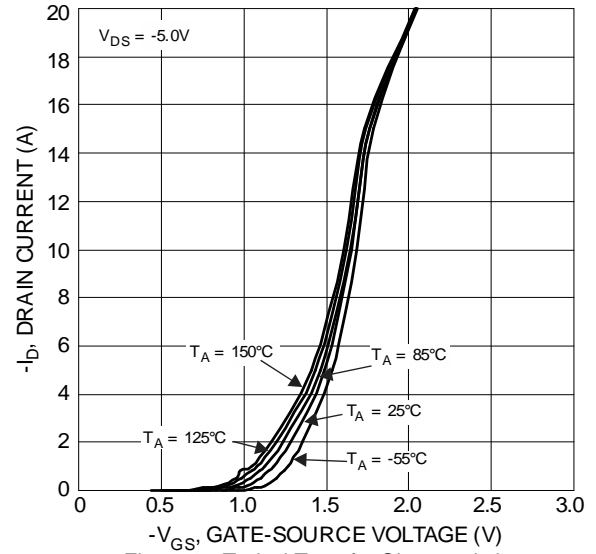


Figure 10 Typical Transfer Characteristics

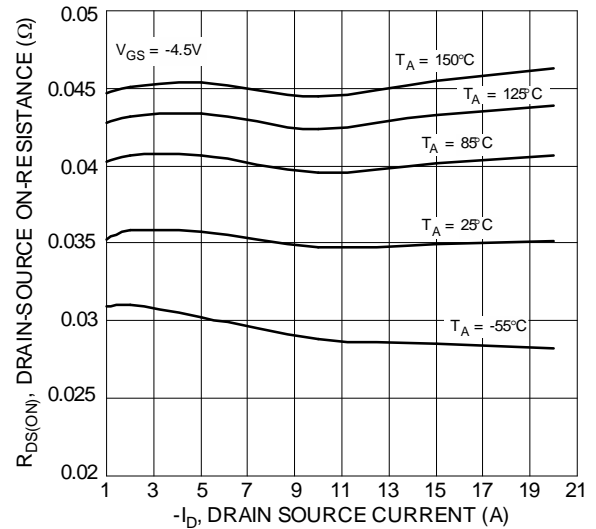


Figure 12 Typical On-Resistance vs. Drain Current and Temperature

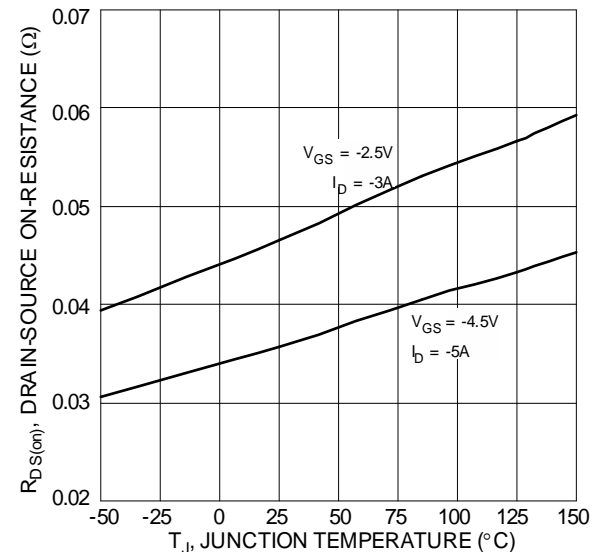


Figure 14 On-Resistance Variation with Temperature

**Q2 P-CHANNEL** (continued)

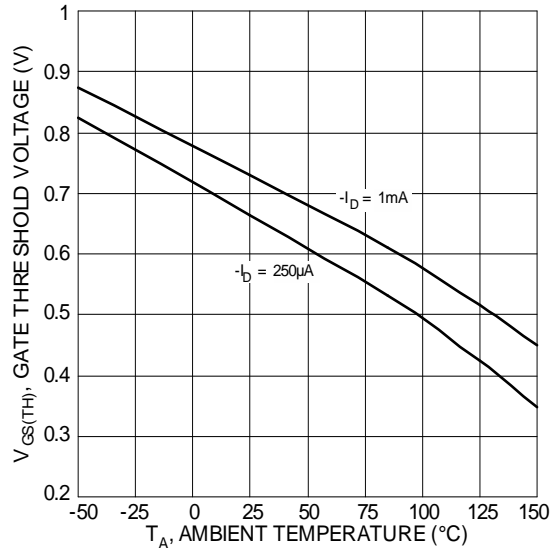


Figure 15 Gate Threshold Variation vs. Ambient Temperature

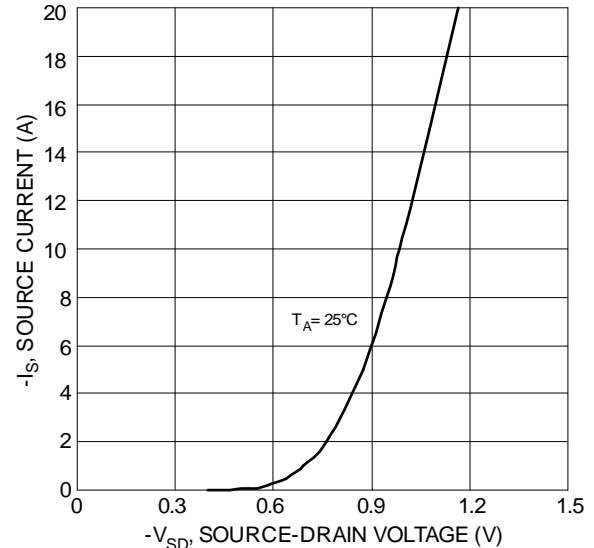


Figure 16 Diode Forward Voltage vs. Current

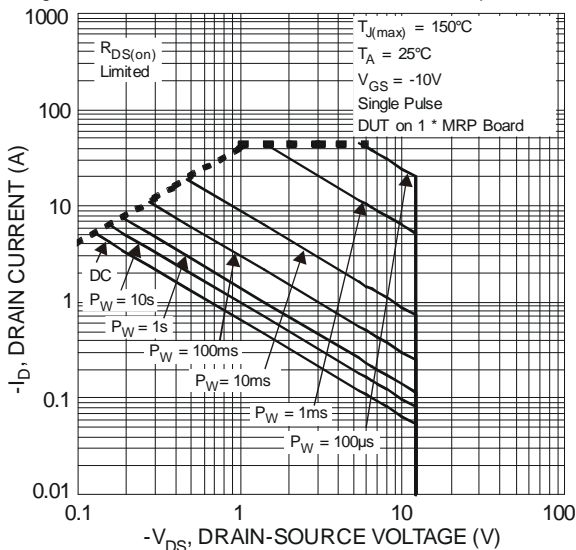


Figure 17 SOA, Safe Operation Area

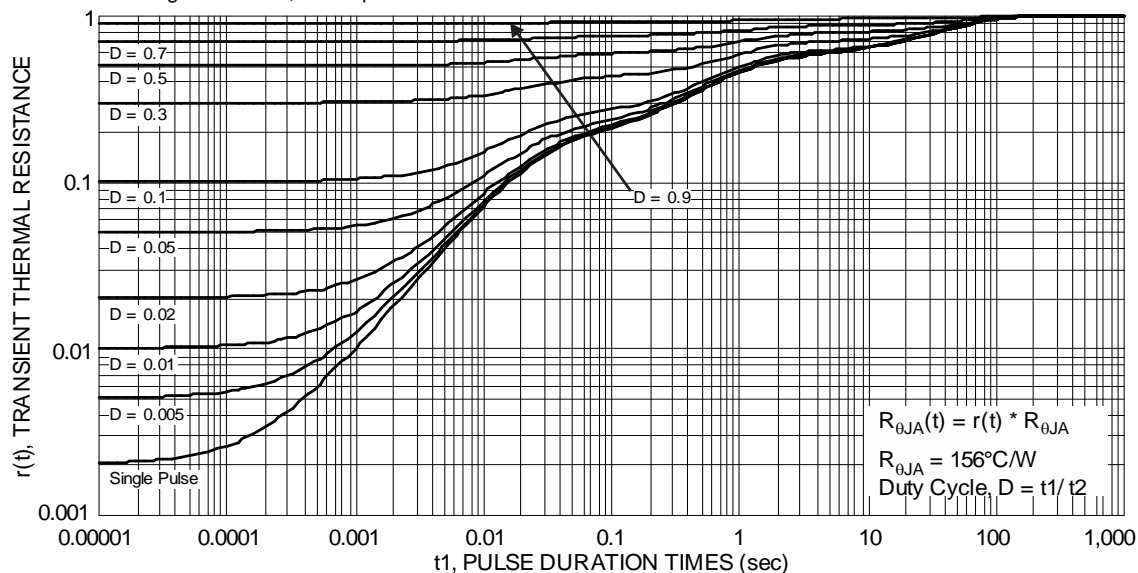
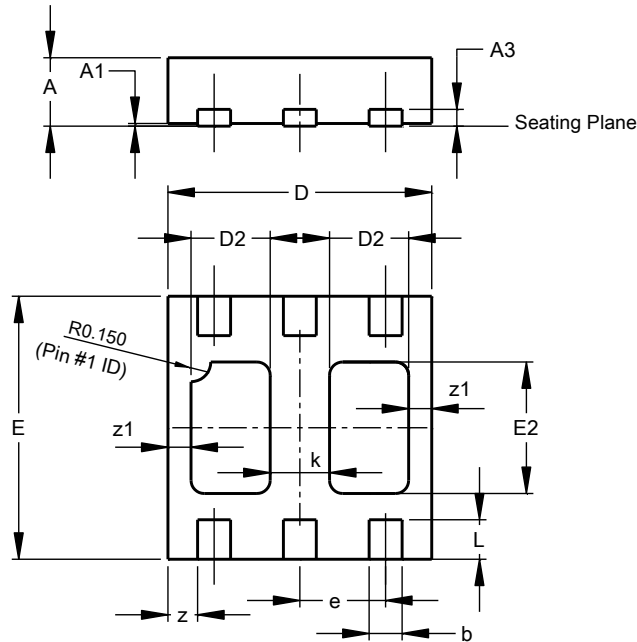


Figure 18 Transient Thermal Resistance

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type B)

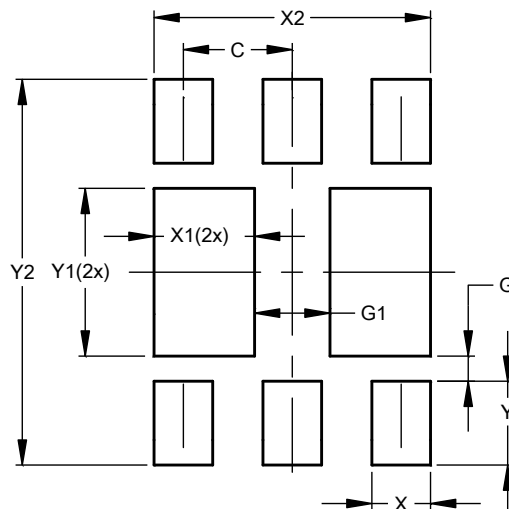


U-DFN2020-6 (Type B)			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0.00	0.05	0.02
A3	-	-	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
D2	0.50	0.70	0.60
e	-	-	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
k	-	-	0.45
L	0.25	0.35	0.30
z	-	-	0.225
z1	-	-	0.175
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type B)



Dimensions	Value (in mm)
C	0.650
G	0.150
G1	0.450
X	0.350
X1	0.600
X2	1.650
Y	0.500
Y1	1.000
Y2	2.300



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2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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